

HA8008

Hot Air Levelling Flux



Product Description

Hasaconi HA8008 is a heat stable organic water-soluble flux, formulated specially for SnPb and Lead Free solder coating of hot air leveling on bare copper boards. It consists of proprietary activators and wetting agents dissolved in a multi-component solvent system. The flux effectively removes the oxides and provides a thick flux coating to the boards from heat damage. The presence of an effective wetting agent assures rapid and uniform penetration of flux to all areas. Hasaconi HA8008 contains no phosphates to prevent wash water disposal problems. It also contains no zinc or ammonium chloride.

Application

Hasaconi HA8008 is specially formulated for use in solder wave-type hot air leveling machines. It can also be used in static solder bath. Adequate and constant flux level should be maintained in the fluxing unit. It is recommended to remove excess flux from printed circuit boards before dipping the boards into the molten solder. This can be done by allowing the boards to dwell over flux tank for a short period of time to drain off excess flux or by means of air knife.

Residue Removal

The flux residue is water soluble. It can be easily removed by rinsing the printed circuit board with warm water (40 - 60 °C).

Recommended Solvent

No solvent is required for this flux.

Health and Safety

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

Specification

Item	Result
State	Viscous Liquid
Colour	Light yellow
Specific Gravity @ 25°C	1.040 +/- 0.003
<small>JIS Z 3197 8.2.2</small>	
Non-volatile Solid Content (110°C, 1hr)	66.0 +/- 2.0 wt%
<small>IPC-TM-650 2.3.34</small>	
<small>JIS Z 3197 8.1.3</small>	
Halide Content	1.10 +/- 0.1%
<small>JIS Z 3197 8.1.4.2.1</small>	
Acid Value Test	19.0 +/- 2 mg KOH/g flux
<small>IPC-TM-650 2.3.13</small>	
<small>JIS Z 3197 8.1.4.1</small>	
<small>JIS Z 3197 8.5.4</small>	
Copper Mirror Test	Classified as "H", Pass
<small>IPC-TM-650 2.3.32</small>	
<small>JIS Z 3197 8.4.2</small>	
Flux Activity Classification	ORH1
<small>IPC J-STD-004</small>	
pH	5.5 +/- 0.5

Storage

Under proper storage condition, HA8008 can be stored for up to 6 months. HA8008 is not flammable. Not recommended to expose under sunlight.

Packaging

Available in 20kg/carboy.

DISCLAIMER OF LIABILITY

"All statements, information and recommendations contained in this catalog are based on data and test results which we consider, to the best of our knowledge and belief, to be reliable and informative to the users but the accuracy and completeness thereof is not guaranteed. No warranty, expressed or implied, statutory or otherwise, is given regarding the use of the information and products contained in this catalog since the conditions and suitability for use, handlings, storage or possession of the products are determined by the users and are therefore beyond our control. We shall not be liable in respect of any liabilities, losses (including consequential losses), damages, proceedings, costs, claims or injuries whatsoever sustained or suffered by the users (including any third parties) in connection with the use of the information, recommendation and the products contained in this catalog."

Singapore Asahi Chemical and Solder Industries Pte Ltd

47 Pandan Road Singapore 609288

Tel: +65 6262-1616 Fax: +65 6261-6311

Website: <http://www.asahisolder.com> Email: enquiry@sinasahi.com.sg